

Wafer Mapping

to the Semiconductor Market



Application Notes

There is always the concern of having faulty operation as a result of reflective rays coming from wafers above or below the sensing target wafer when using a thru scan type sensor to detect the wafer in a cassette. However, a narrow beam type fiber optic sensor can make stable detection of the target wafer without any of the adverse effects from reflective light coming from the surrounding wafers.

Applications

Loaders
Unloaders

Features and Benefits

Parallel beams of $\pm 2^\circ$

- Fine parallel beams ($\pm 2^\circ$) equivalent to a laser beam can avoid any adverse effects resulting from light reflecting from surrounding wafers. (HPF-T023)

Long scanning distance

- A long scanning distance is achieved with the HPF-T020 (1600mm scanning distance) and the HPF-T023 (1200mm scanning distance) when used with the HPX-H1.

Flexible mounting positions

- A top-view type (HPF-T023) and a side-view type (HPF-T020) are available. Selection can be made depending on the requirements of the mounting space.

Custom orders available

- Custom designs can be ordered to meet the customer's various needs.
- Please contact us at Yamatake regarding fiber length, mounting shape, spaces, etc.

Yamatake Products

Narrow beaming top-view thru scan type: **HPF-T023**

Parallel beaming side-view thru scan type: **HPF-T020**

Combination type fiber optic sensor: **HPX Series**

Auto-tuning type: **HPX-T Series**

